

## -12V P-Channel Power MOSFET

### DESCRIPTION :

- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

$V_{DSS}$	-12V
$I_D$	-4.1A
$R_{DS(ON)_MAX. @V_{GS}=-4.5V}$	36m $\Omega$

### TYPICAL APPLICATIONS :

- PWM Applications
- Load Switch
- Power Management



SOT-23

### MAXIMUM RATINGS (at $T_c = 25^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	-12	V
Gate-Source Voltage	$V_{GSS}$	$\pm 8$	V
Continuous Drain Current TC = 25°C TC = 100°C	$I_D$	-4.1 -2.6	A
Pulsed Drain Current, $t_p < 10\mu\text{s}^{(1)}$	$I_{DM}$	-34	A
Power dissipation	$P_D$	1.7	W
Junction & Storage temperature Range	$T_J, T_{STG}$	-55~+150	°C

Notes : 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

### THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient	$R_{\theta JA}$	74	°C/W

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage $V_{GS} = 0\text{V}$ , $I_D = -250\mu\text{A}$	$V_{(BR)DSS}$	-12			V
Zero Gate Voltage Drain Current $V_{DS} = -12\text{V}$ , $V_{GS} = 0\text{V}$	$I_{DSS}$			-1	$\mu\text{A}$
Gate-Source Leakage Current $V_{GS} = \pm 8\text{V}$ , $V_{DS} = 0\text{V}$	$I_{GSS}$			$\pm 100$	nA
Gate-Source threshold voltage $V_{DS} = V_{GS}$ , $I_D = -250\mu\text{A}$	$V_{GS(th)}$	-0.4	-0.65	-1.0	V
Drain-Source On-State Resistance $V_{GS} = -4.5\text{V}$ , $I_D = -4.1\text{A}$ $V_{GS} = -2.5\text{V}$ , $I_D = -3\text{A}$	$R_{DS(on)}$		26 35	36 53	m $\Omega$
Input capacitance $f=1\text{MHz}$ , $V_{DS}=-4\text{V}$ , $V_{GS}=0\text{V}$	$C_{iss}$		905		pF
Output capacitance $f=1\text{MHz}$ , $V_{DS}=-4\text{V}$ , $V_{GS}=0\text{V}$	$C_{oss}$		210		pF
Reverse transfer capacitance $f=1\text{MHz}$ , $V_{DS}=-4\text{V}$ , $V_{GS}=0\text{V}$	$C_{rss}$		195		pF
Total Gate Charge $V_{DS}=-4\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D = -4.1\text{A}$	$Q_g$		7.8	12	nC
Gate-Source Charge $V_{DS}=-4\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D = -4.1\text{A}$	$Q_{gs}$		1.2		nC
Gate-Drain("Miller") Charge $V_{DS}=-4\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D = -4.1\text{A}$	$Q_{gd}$		1.6		nC
Turn-on delay time $V_{DD} = -4\text{V}$ , $V_{ID} = -3.3\text{A}$ , $R_G = 1.0\Omega$ , $V_{GEN} = -4.5\text{V}$ , $R_L = 1.2\Omega$	$t_{d(ON)}$		13	20	ns
Rise time $V_{DD} = -4\text{V}$ , $V_{ID} = -3.3\text{A}$ , $R_G = 1.0\Omega$ , $V_{GEN} = -4.5\text{V}$ , $R_L = 1.2\Omega$	$t_r$		35	53	ns
Turn-off delay time $V_{DD} = -4\text{V}$ , $V_{ID} = -3.3\text{A}$ , $R_G = 1.0\Omega$ , $V_{GEN} = -4.5\text{V}$ , $R_L = 1.2\Omega$	$t_{d(OFF)}$		32	48	ns
Fall time $V_{DD} = -4\text{V}$ , $V_{ID} = -3.3\text{A}$ , $R_G = 1.0\Omega$ , $V_{GEN} = -4.5\text{V}$ , $R_L = 1.2\Omega$	$t_f$		10	20	ns
Maximum Continuous Drain to Source Diode Forward Current	$I_S$			-4.1	A
Maximum Pulsed Drain to Source Diode Forward Current	$I_{SM}$			-0.52	A
Diode Forward Voltage $V_{GS} = 0\text{V}$ , $I_S = -4.1\text{A}$	$V_{SD}$			-2.2	V
Reverse Recovery Time $V_{GS} = 0\text{V}$ , $I_S = -4.1\text{A}$ , $di/dt = 100\text{A}/\mu\text{s}$	$t_{rr}$		20		ns
Reverse Recovery Charge $V_{GS} = 0\text{V}$ , $I_S = -4.1\text{A}$ , $di/dt = 100\text{A}/\mu\text{s}$	$Q_{rr}$		9		nC

Typical Performance Characteristics

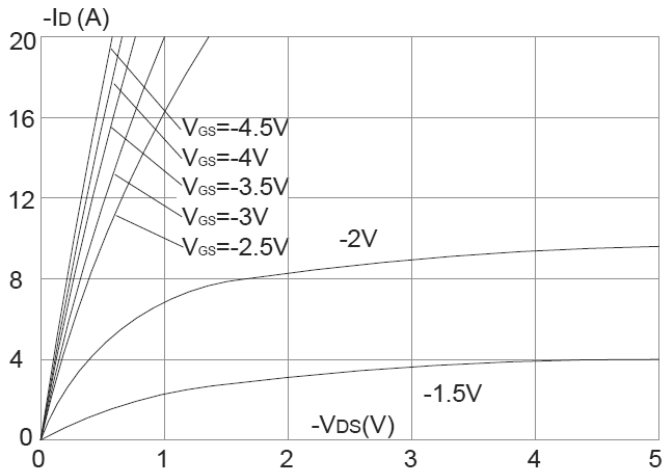


Figure 1. Output Characteristics

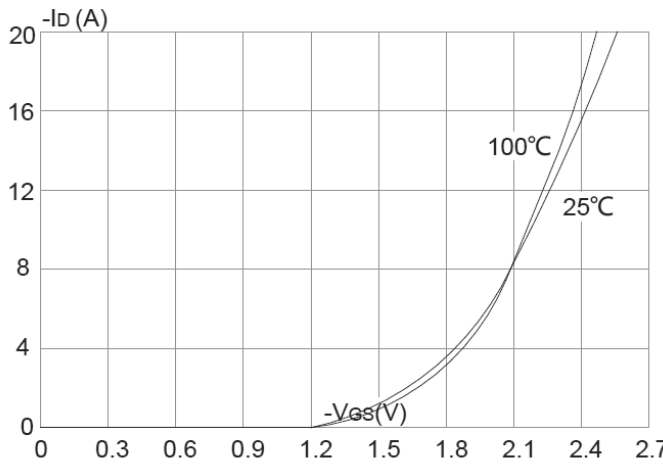


Figure 2. Typical Transfer Characteristics

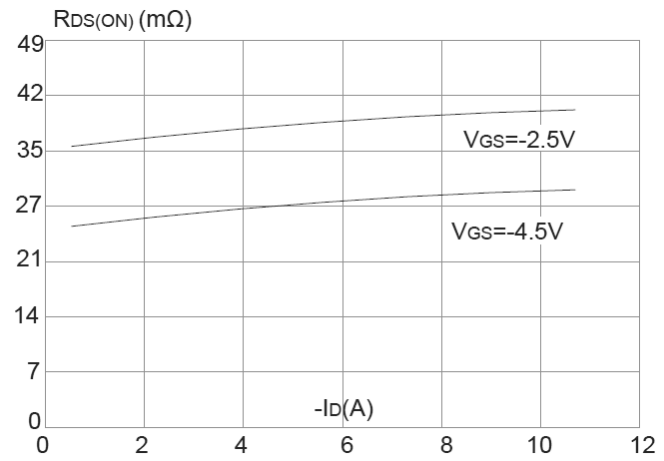


Figure 3. On-resistance vs. Drain Current

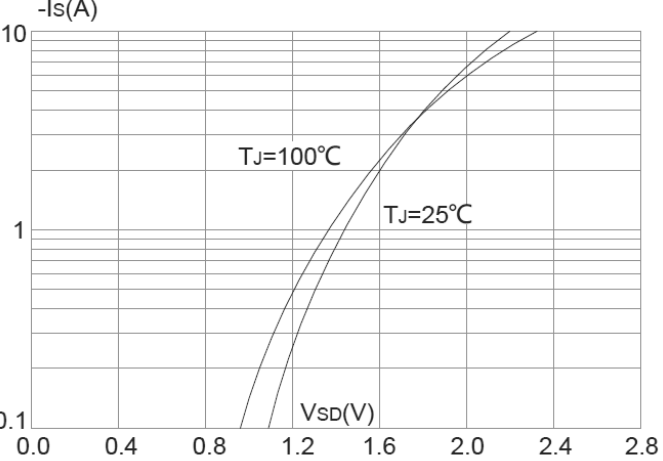


Figure 4. Body Diode Characteristics

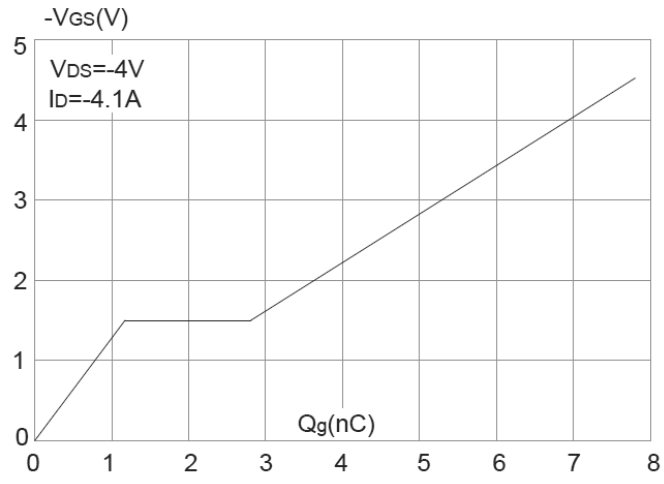


Figure 5. Gate Charge Characteristics

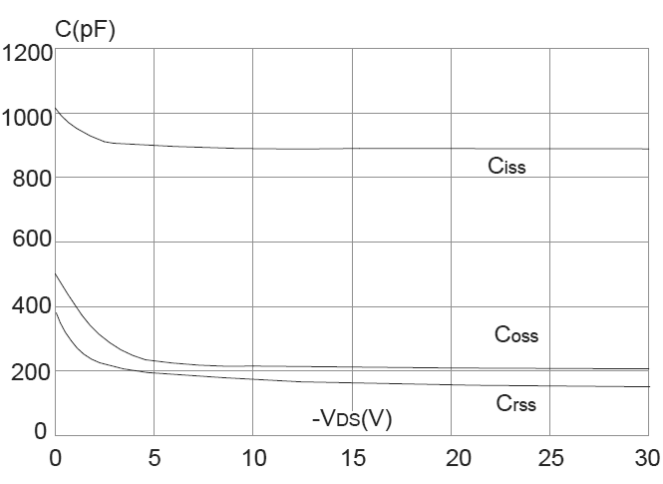


Figure 6. Capacitance Characteristics

Typical Performance Characteristics

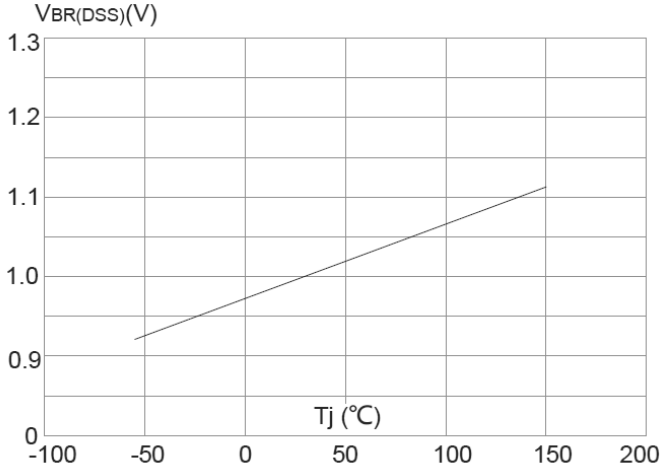


Figure 7. Normalized Breakdown Voltage vs. Junction Temperature

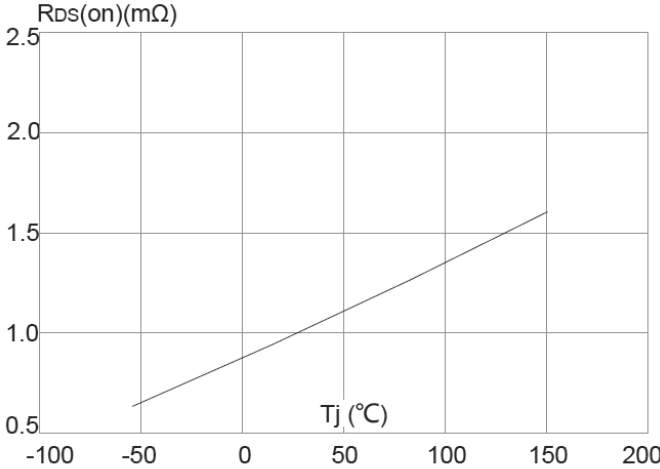


Figure 8. Normalized on Resistance vs. Junction Temperature

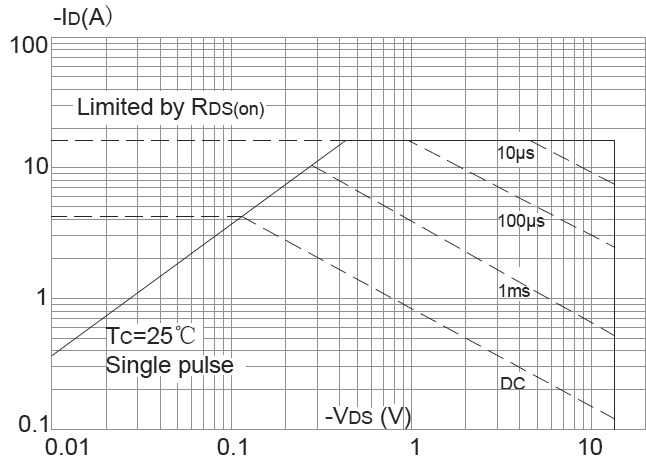


Figure 9. Maximum Safe Operating Area

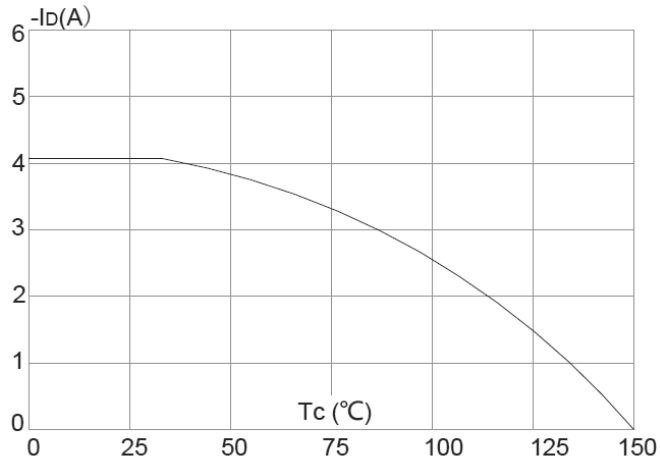


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

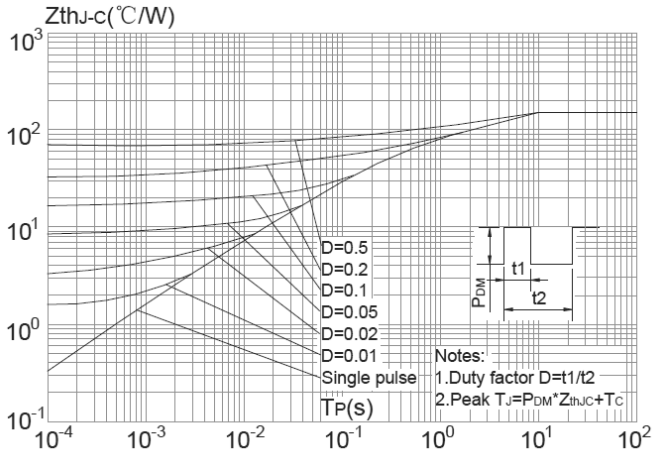
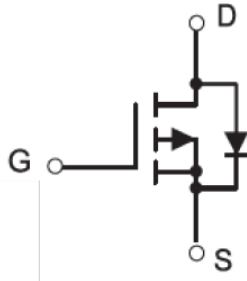
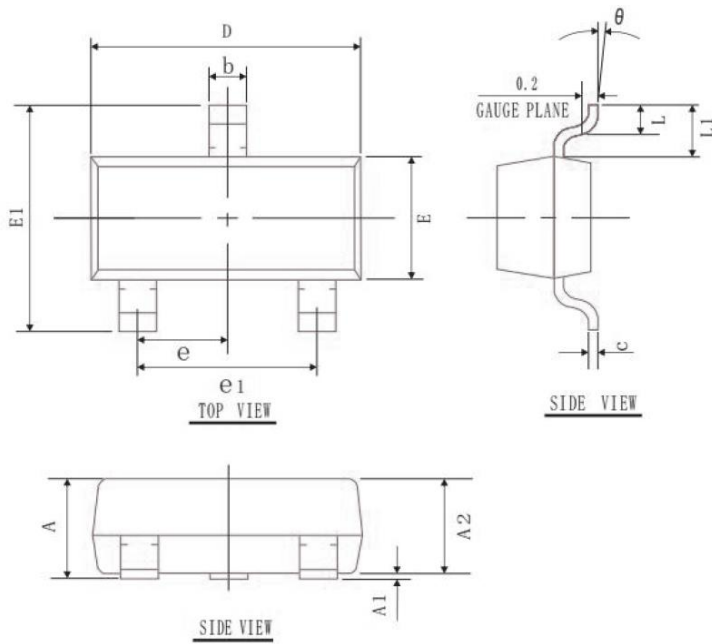


Figure 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

·Circuit diagram



·Package outlines : Dimensions in (mm)



SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A1	0.00	0.05	0.10
A2	0.90	1.00	1.10
b	0.30	0.40	0.50
c	0.08	0.10	0.15
D	2.80	2.90	3.00
E	1.20	1.30	1.40
E1	2.30	2.40	2.50
L	0.30	0.40	0.50
θ	0°	5°	10°
L1	0.55 REF		
e	0.95 BSC		
e1	1.90 REF		

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